

AMENDMENTS TO THE CLAIMS

Claim 1 (currently amended) A method of manufacturing a wiring substrate, comprising the steps of:

preparing a substrate having an insulating body and a conductive pattern having electrodes formed on the insulating body, the electrodes on which connection pads of an electronic part are connected;

adhering a catalytic metal serving as a catalyst of an electroless plating onto the insulating body and the conductive pattern;

coating selectively an oxidizing agent, which can oxidize the catalytic metal and make the catalytic metal in an inactive state to the electroless plating, on the catalytic metal in a space portion between the electrodes of the conductive pattern; and

forming selectively a metal layer on the conductive pattern by the electroless plating,

wherein the conductive pattern is arranged in a state such that the distance between the electrodes of the conductive pattern in the space portion between the electrodes has a plurality of different values, the oxidizing agent is selectively coated to only coat all parts of the space portion in which the distance between the electrodes is smaller than 30 μm in order to prevent short circuits, ~~the space portion smaller than 30 μm being where the short circuits tend to remarkably occur.~~

Claim 2 (canceled)

Claim 3 (previously presented) The method of manufacturing a wiring substrate according to claim 1, wherein the step of selectively coating the oxidizing agent is carried out by an ink jet method.

Claim 4 (previously presented) The method of manufacturing a wiring substrate according to claim 1, wherein the step of adhering the catalytic metal onto the insulating body and the conductive pattern includes the step of coating an activating solution containing ions of the catalytic metal to deposit the catalytic metal by an oxidation-reduction reaction.

Claims 5-6 (canceled)

Claim 7 (previously presented) The method of manufacturing a wiring substrate according to claim 1, wherein the catalytic metal is palladium, and the metal layer formed by the electroless plating is a nickel layer or a copper layer.

Claim 8 (canceled)

Claim 9 (canceled)

Claim 10 (previously presented) The method of manufacturing a wiring substrate according to claim 1, wherein the oxidizing agent is one of an H_2SO_4 solution and a mixed solution consisting of H_2SO_4 and HCl .

Claim 11 (canceled)

Claim 12 (canceled)